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(12) **United States Design Patent**
Shi et al.

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(45) **Date of Patent:** **** Jul. 12, 2016**

(54) **PACKAGE FOR LIGHT-EMITTING DIODE**

(56) **References Cited**

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(72) Inventors: **Junpeng Shi**, Xiamen (CN); **Pei-Song Cai**, Xiamen (CN); **Zhenduan Lin**, Xiamen (CN); **Hao Huang**, Xiamen (CN)

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

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CPC ... H01L 25/167; H01L 25/0753; H01L 27/15;
H01L 27/156; H01L 31/02; H01L 33/00;
H01L 33/04; H01L 33/08; H01L 33/10;
H01L 33/20; H01L 33/38; H01L 33/42;
H01L 33/48; H01L 33/62; H01L 33/483;
H01L 33/486; F21K 9/00; F21K 9/30; F21K
9/54

See application file for complete search history.

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Primary Examiner — Selina Sikder

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(57) **CLAIM**

The ornamental design for a package for light-emitting diode, substantially as shown and described.

DESCRIPTION

FIG. 1 is a front view of a package for light emitting diode according to a first embodiment of the disclosure;
FIG. 2 is a rear view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 3 is a left side view of a package for light emitting diode according to the first embodiment of the disclosure;

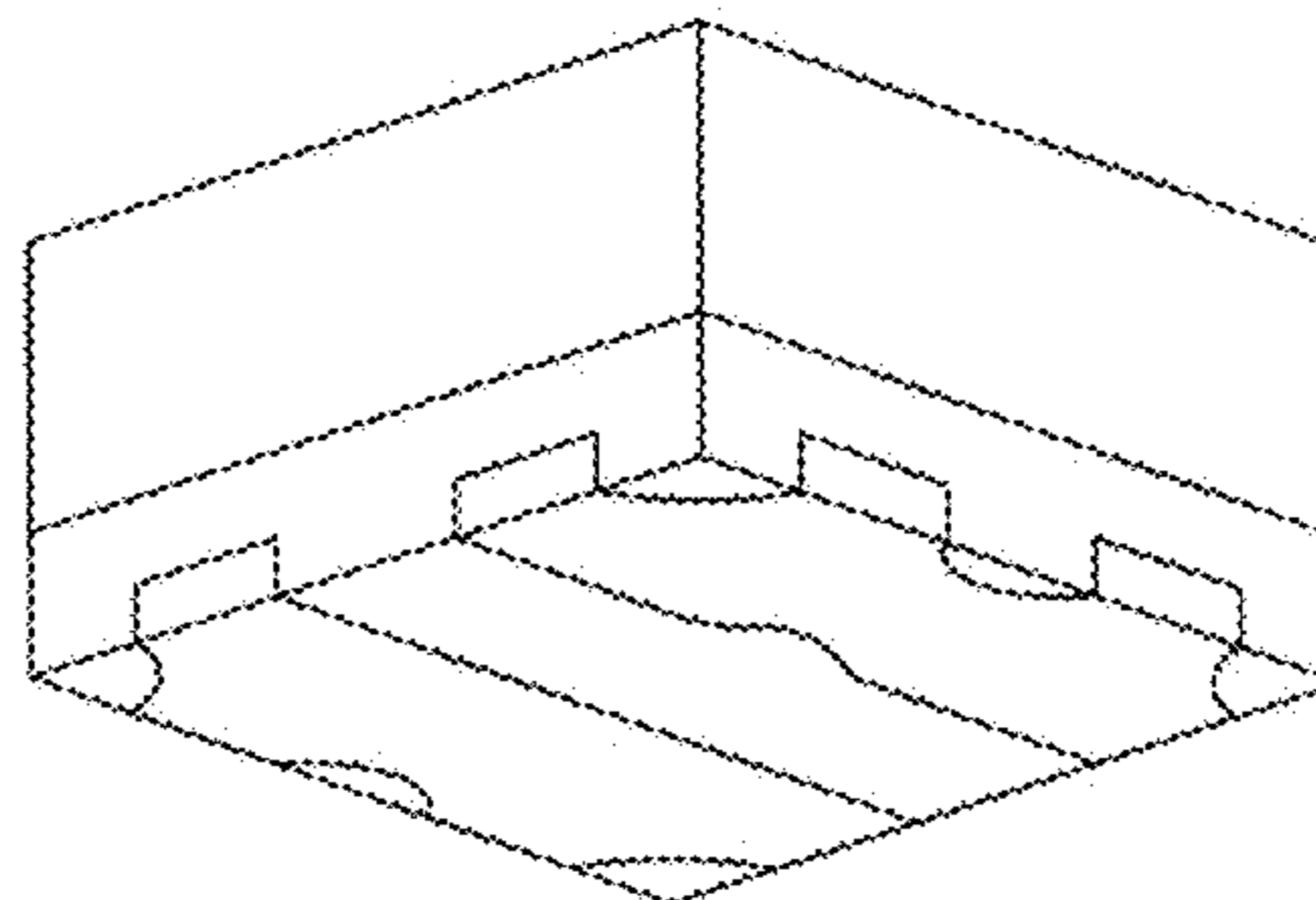
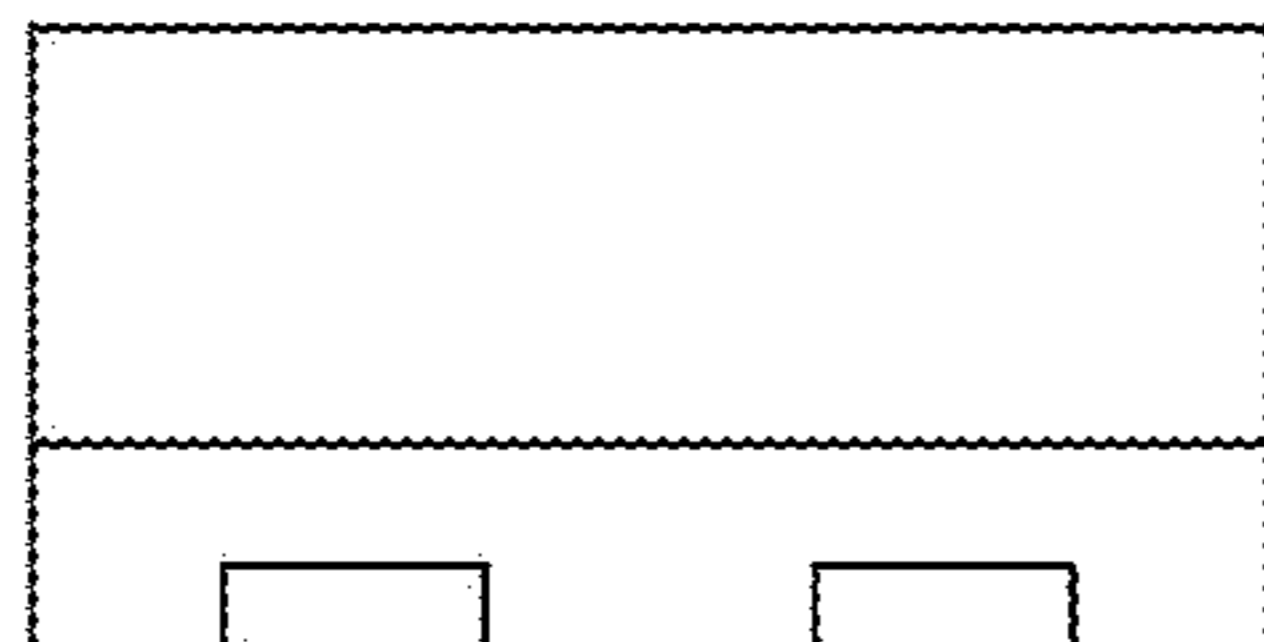


FIG. 4 is a right side view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 5 is a top view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 6 is a bottom view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 7 is a perspective view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 8 is another perspective view of a package for light emitting diode according to the first embodiment of the disclosure;
FIG. 9 is a front view of a package for light emitting diode according to a second embodiment of the disclosure;
FIG. 10 is a rear view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 11 is a left side view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 12 is a right side view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 13 is a top view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 14 is a bottom view of a package for light emitting diode according to the second embodiment of the disclosure;

FIG. 15 is a perspective view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 16 is another perspective view of a package for light emitting diode according to the second embodiment of the disclosure;
FIG. 17 is a front view of a package for light emitting diode according to a third embodiment of the disclosure;
FIG. 18 is a rear view of a package for light emitting diode according to the third embodiment of the disclosure;
FIG. 19 is a left side view of a package for light emitting diode according to the third embodiment of the disclosure;
FIG. 20 is a right side view of a package for light emitting diode according to the third embodiment of the disclosure;
FIG. 21 is a top view of a package for light emitting diode according to the third embodiment of the disclosure;
FIG. 22 is a bottom view of a package for light emitting diode according to the third embodiment of the disclosure;
FIG. 23 is a perspective view of a package for light emitting diode according to the third embodiment of the disclosure;
and,
FIG. 24 is another perspective view of a package for light emitting diode according to the third embodiment of the disclosure.

1 Claim, 9 Drawing Sheets

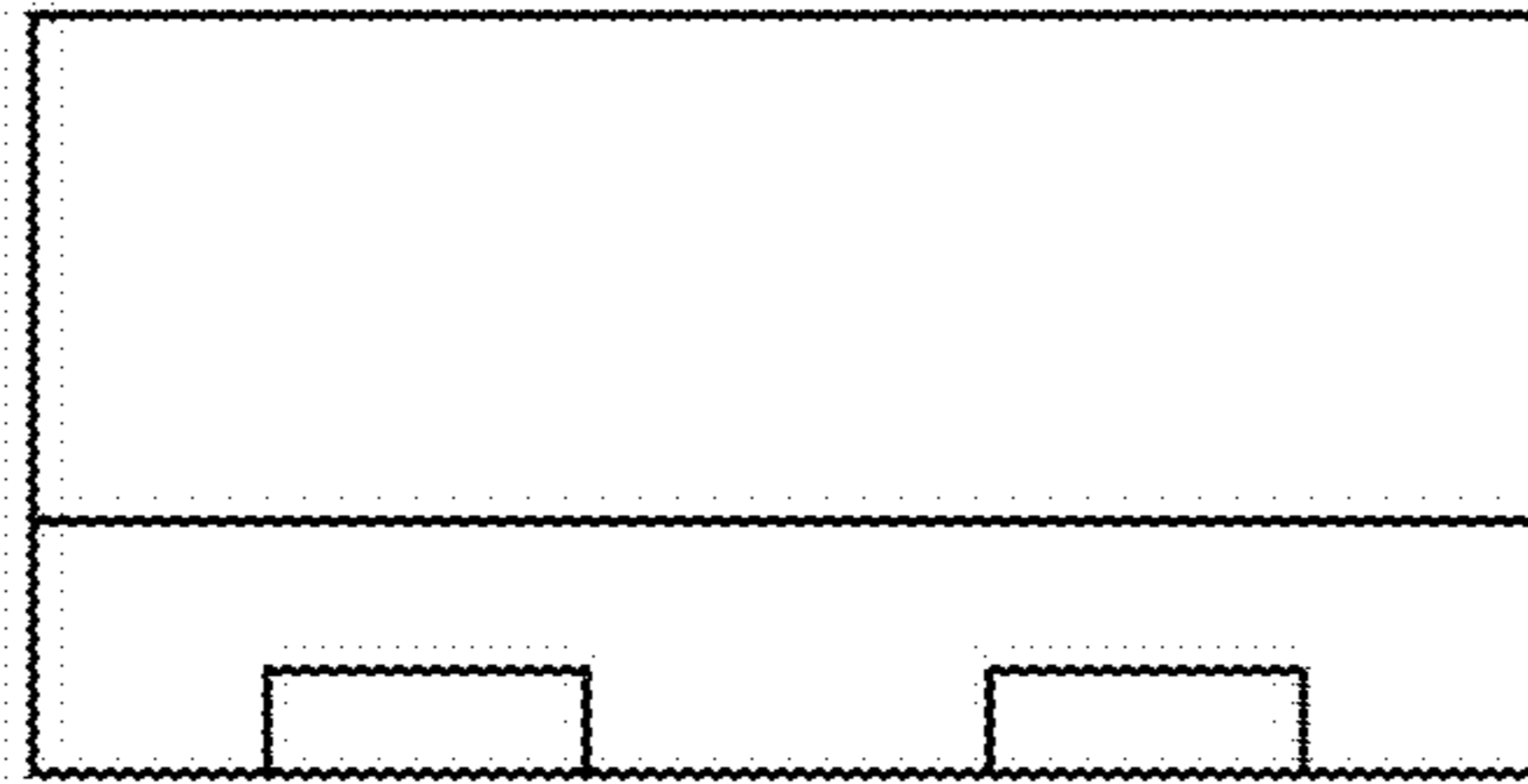


FIG. 1

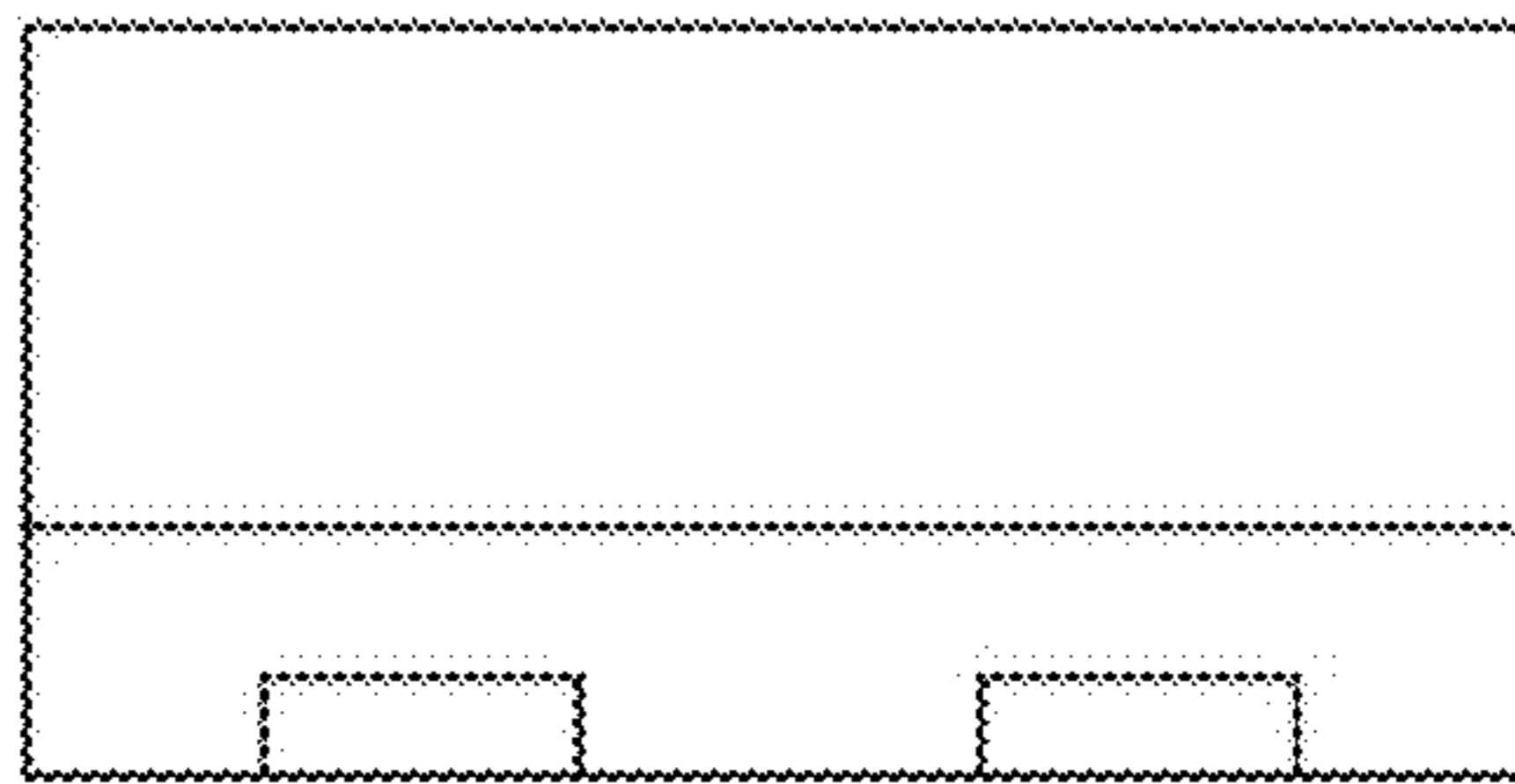


FIG. 2

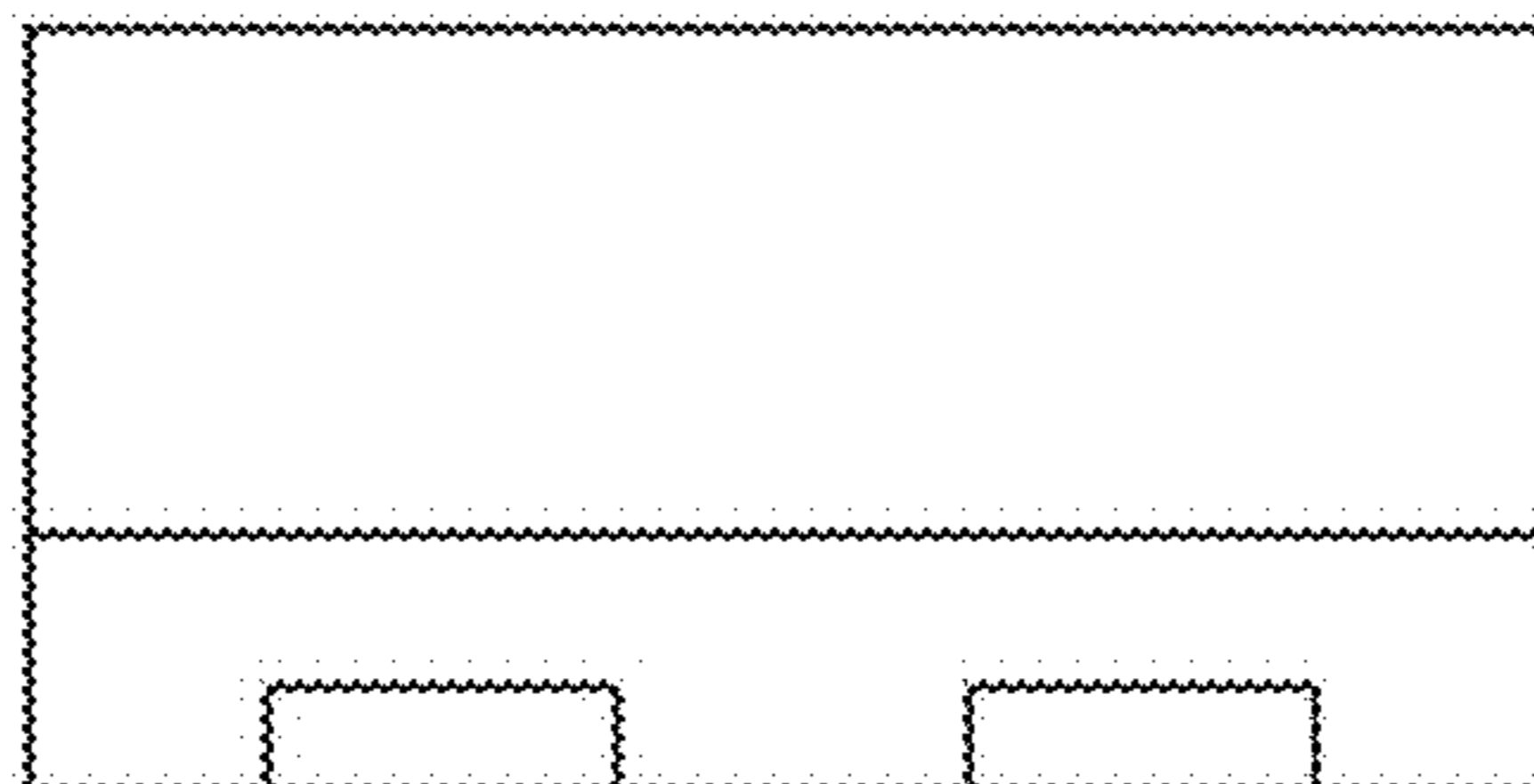


FIG. 3

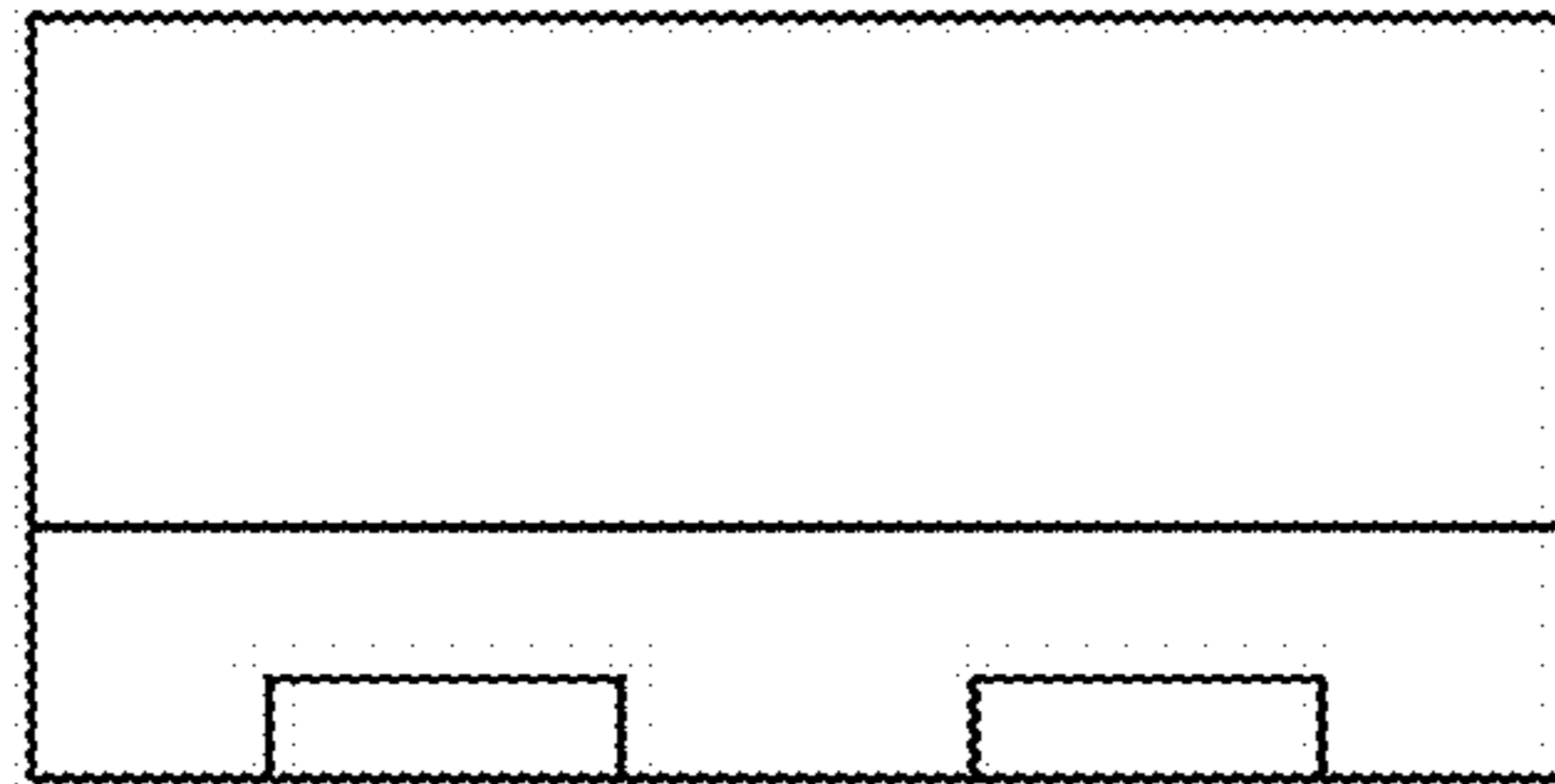


FIG. 4

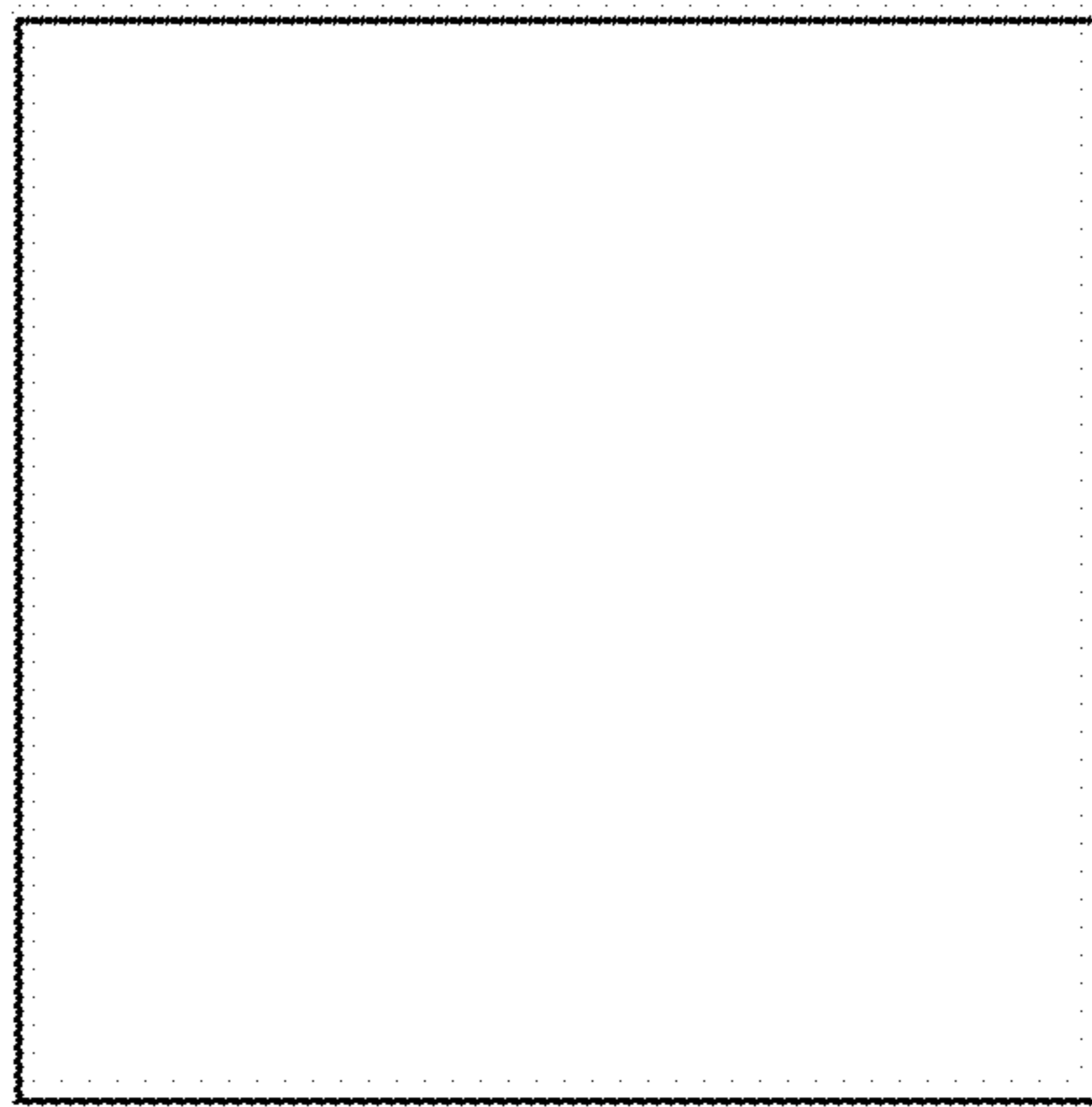


FIG. 5

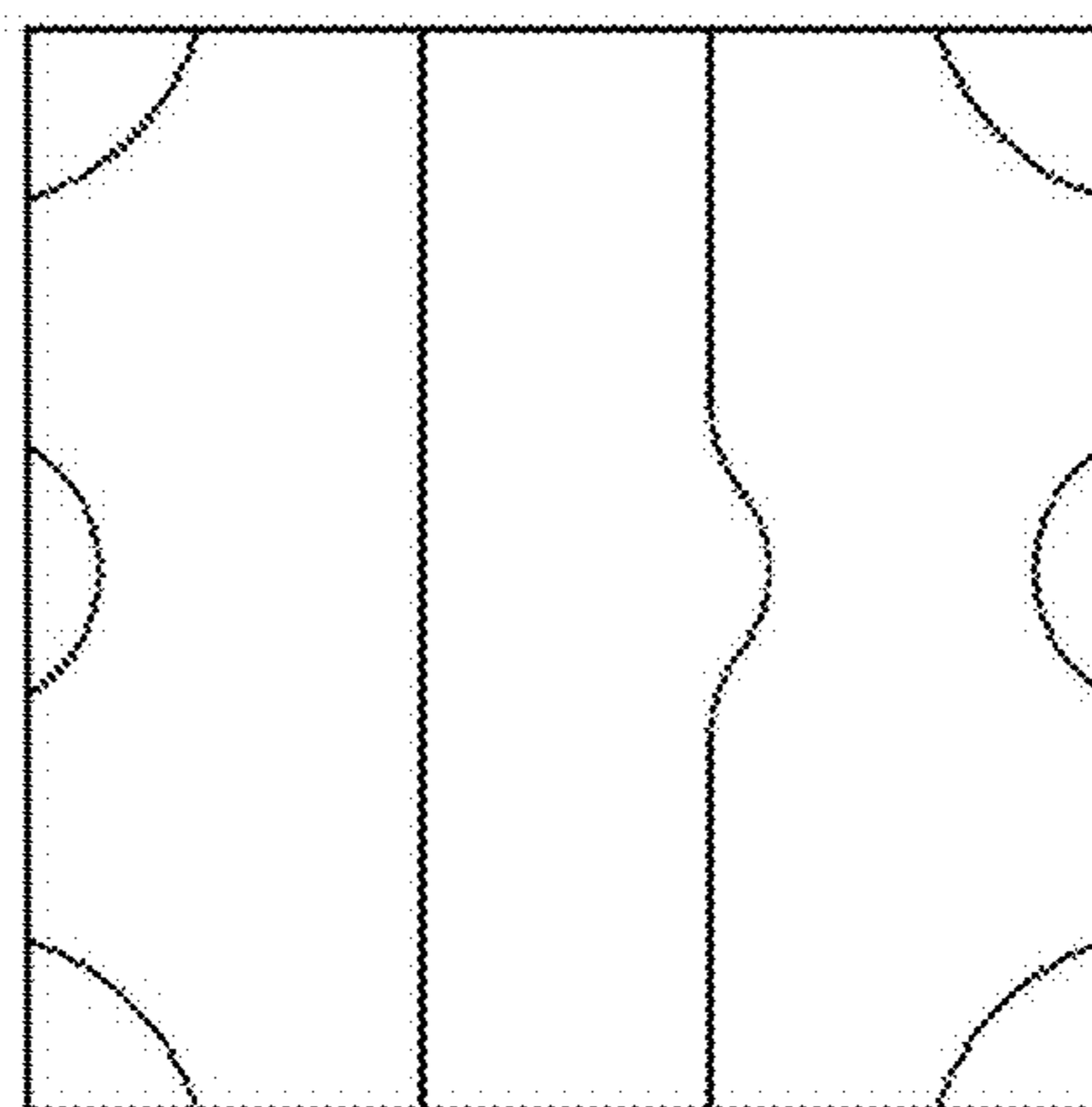


FIG. 6

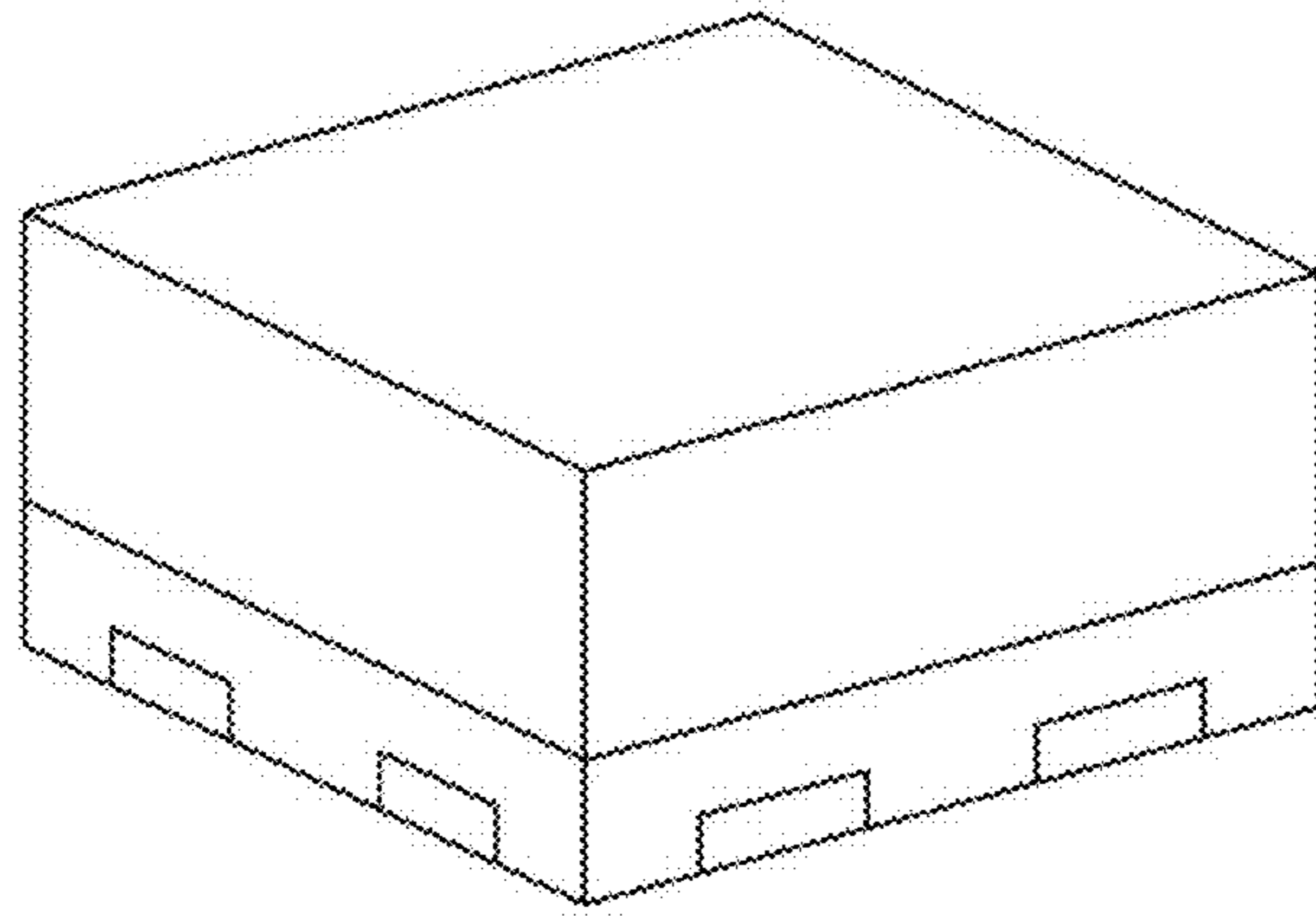


FIG. 7

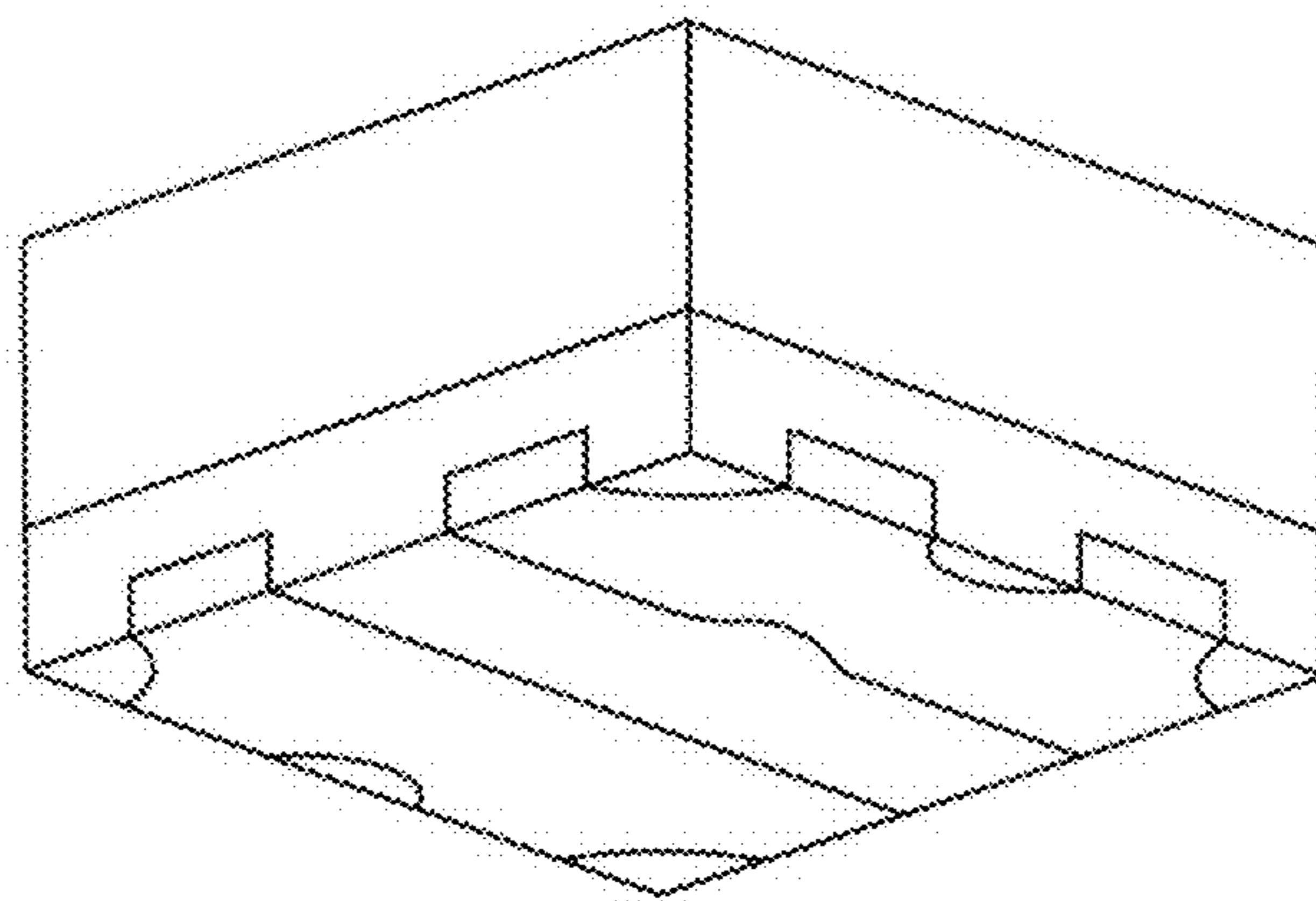


FIG. 8

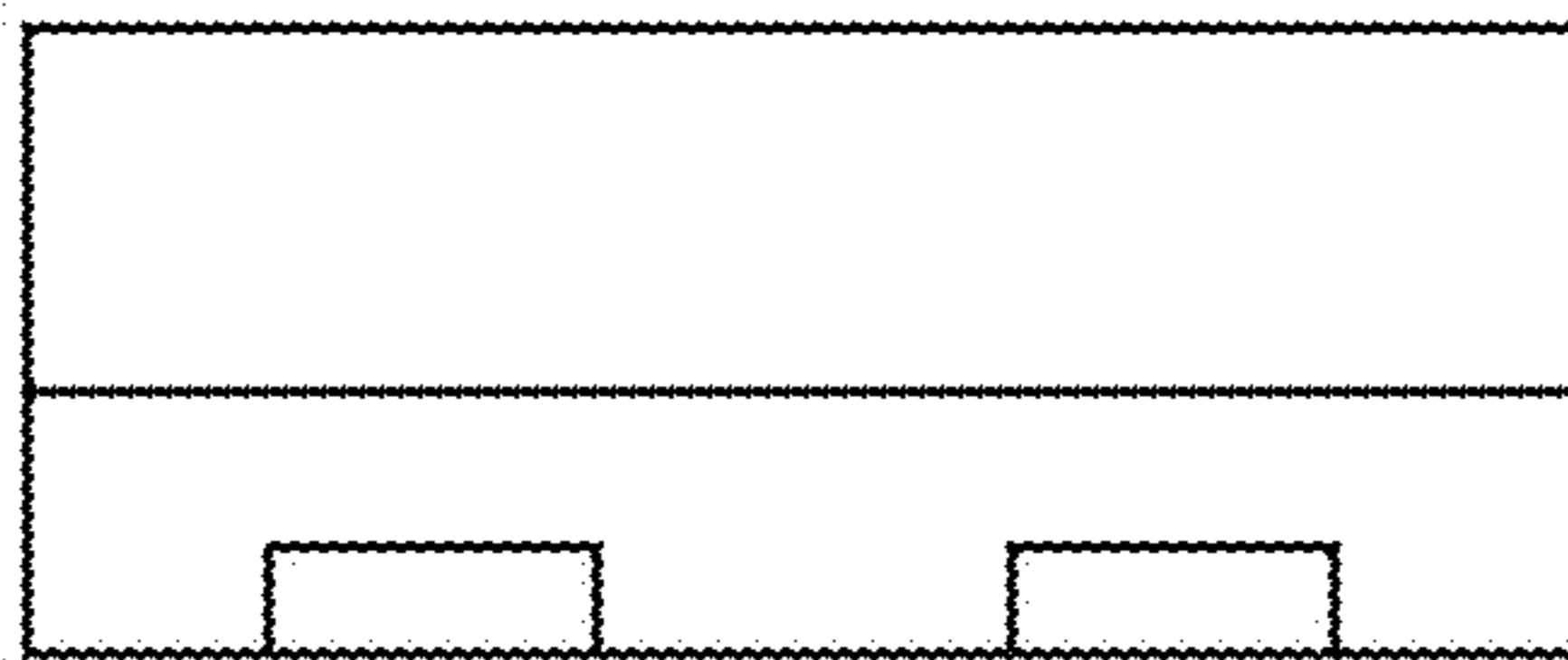


FIG. 9

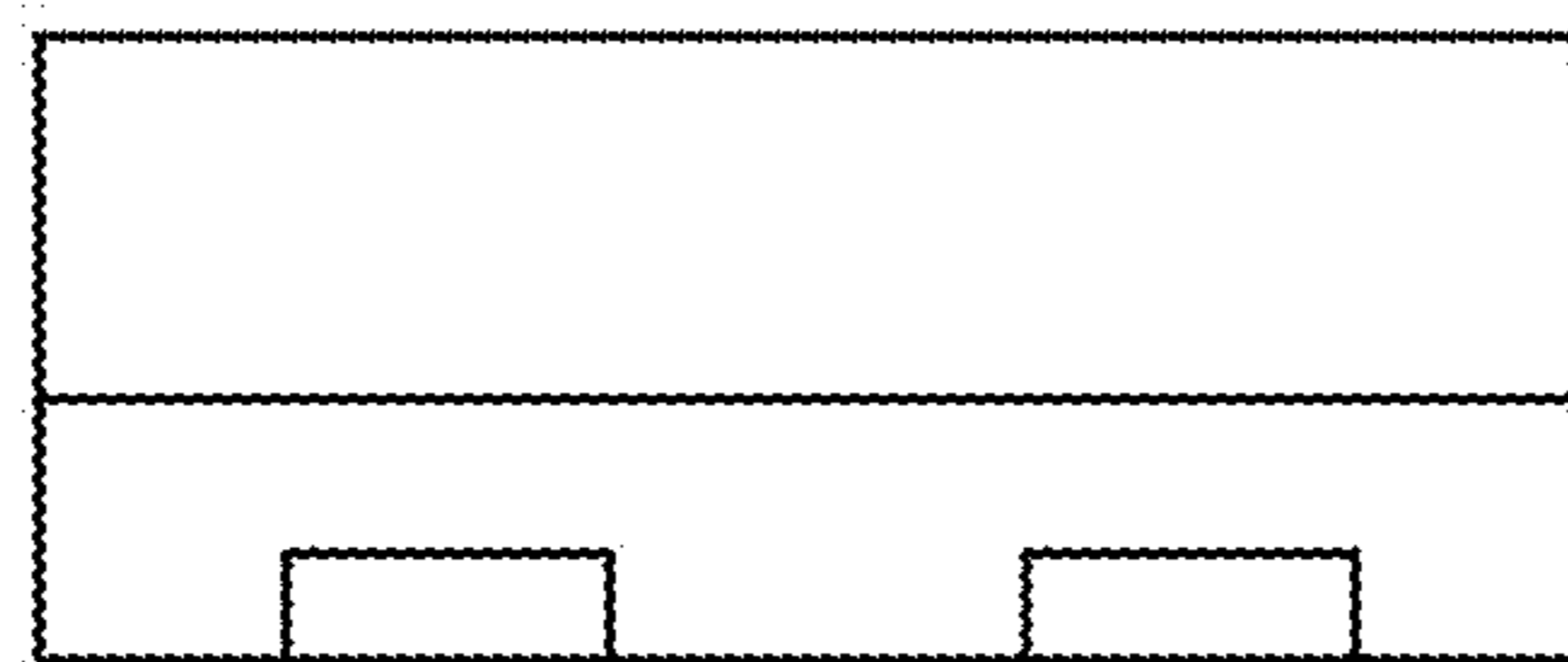


FIG. 10

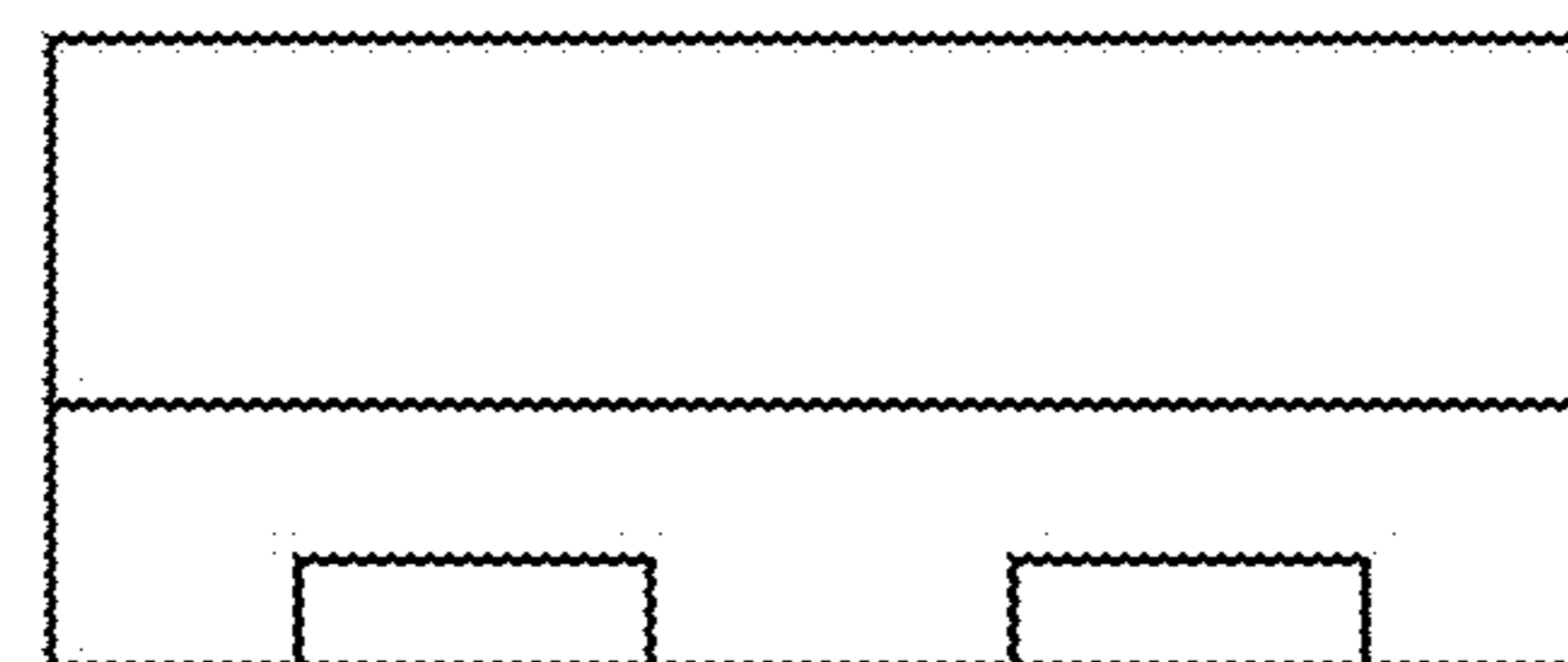


FIG. 11

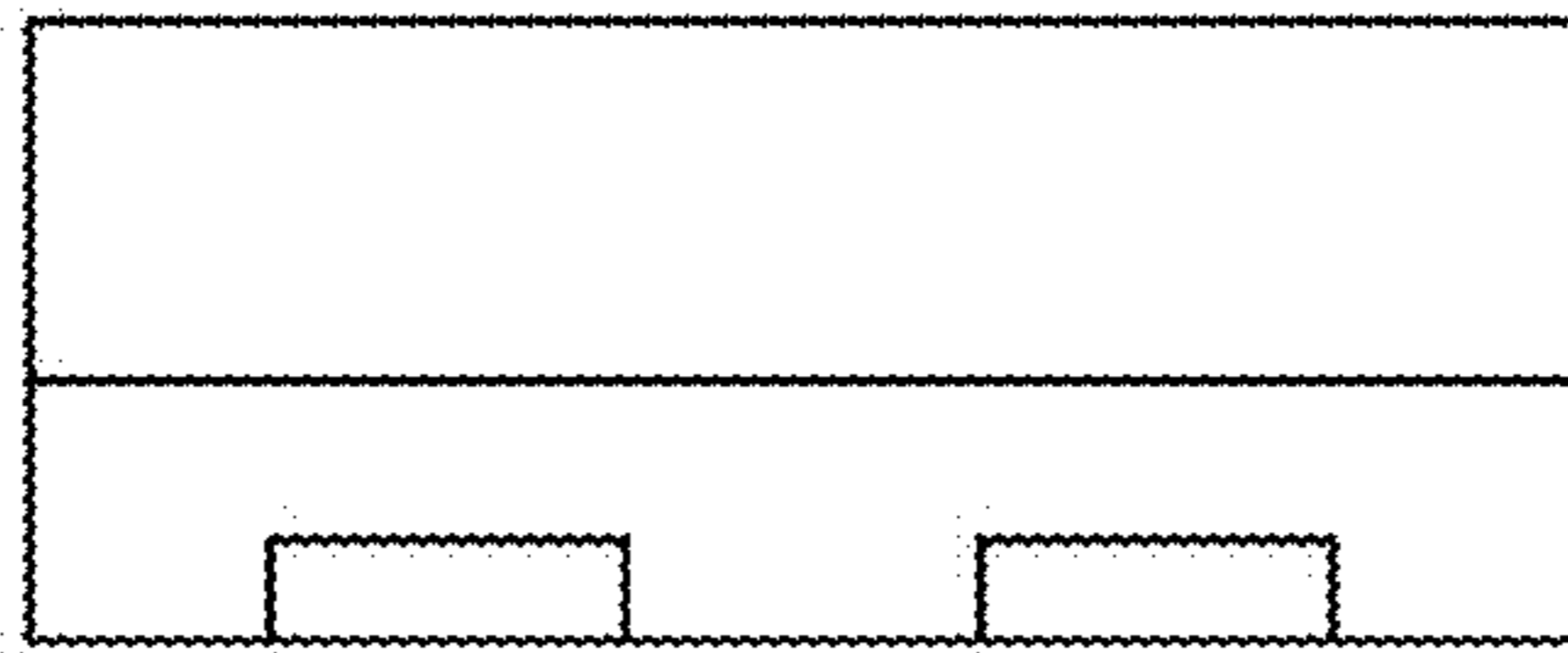


FIG. 12

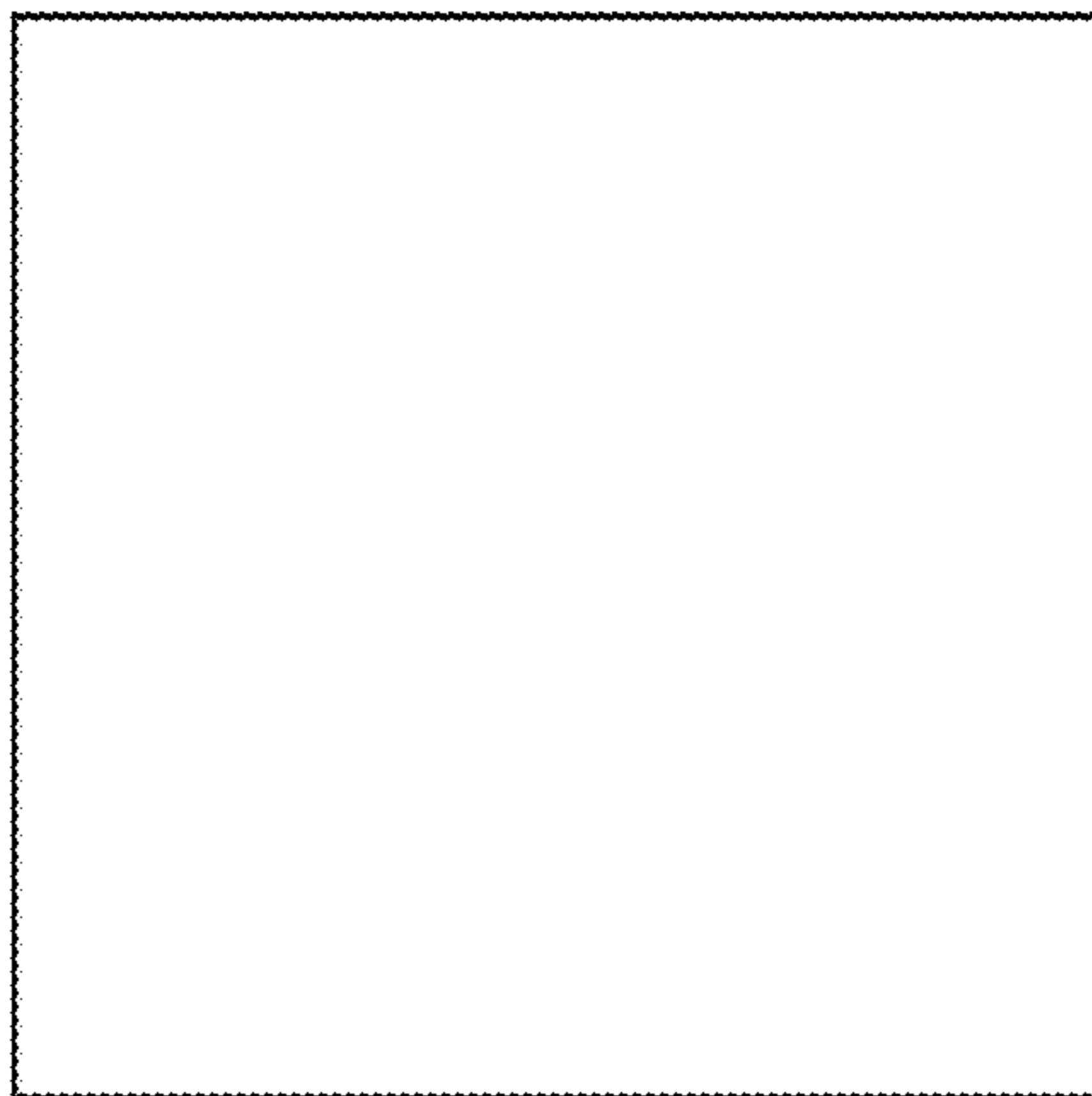


FIG. 13

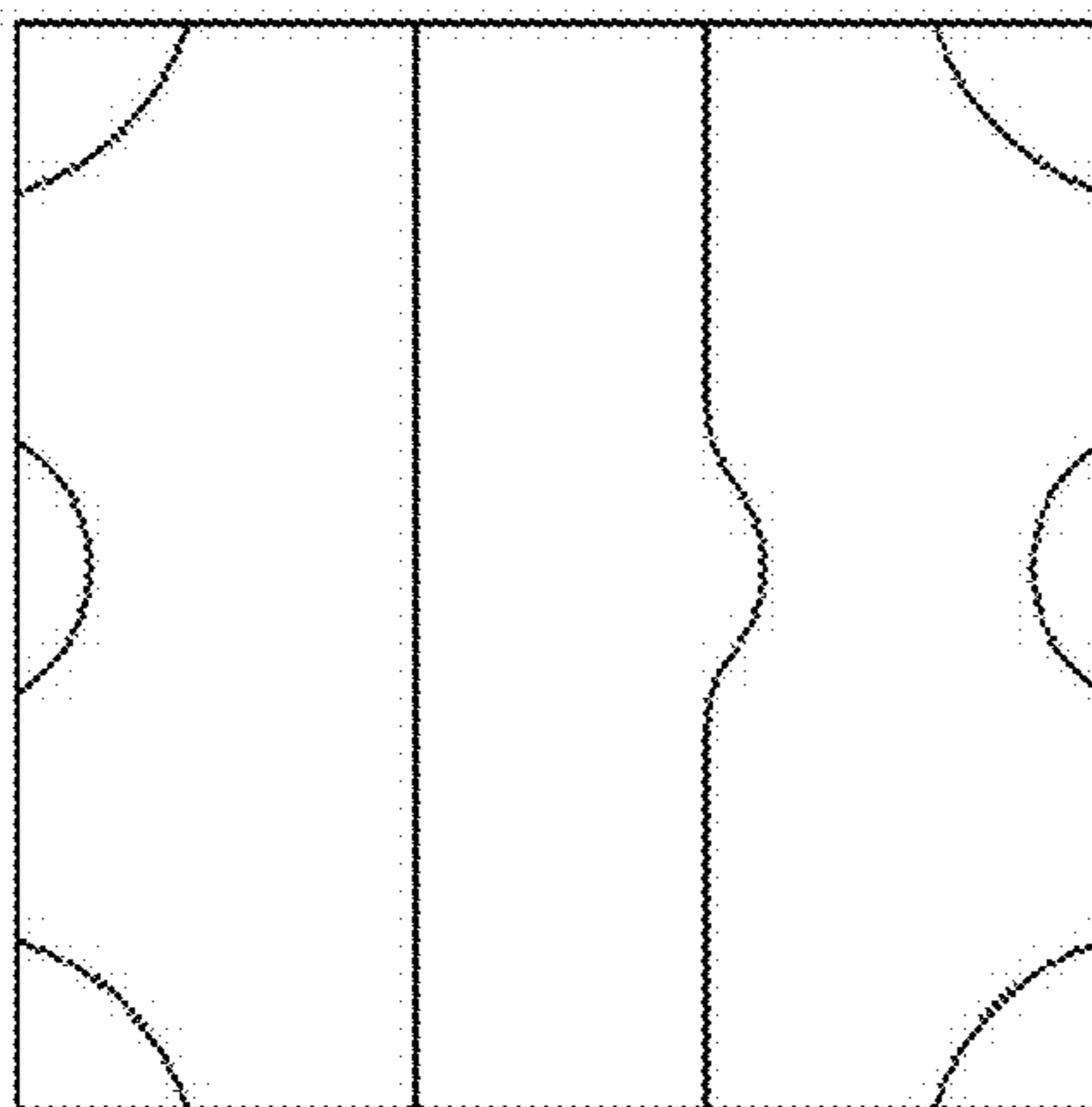


FIG. 14

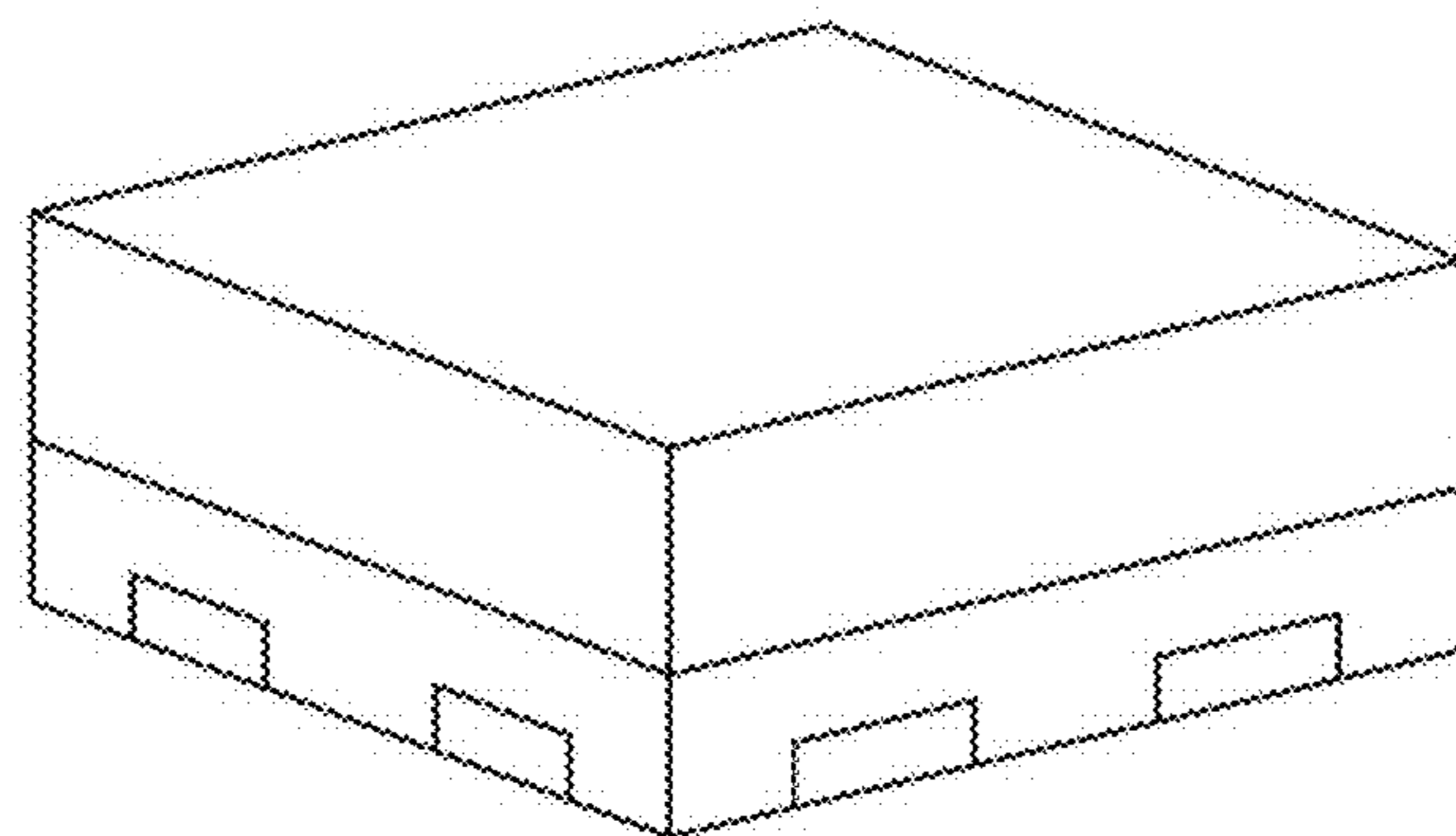


FIG. 15

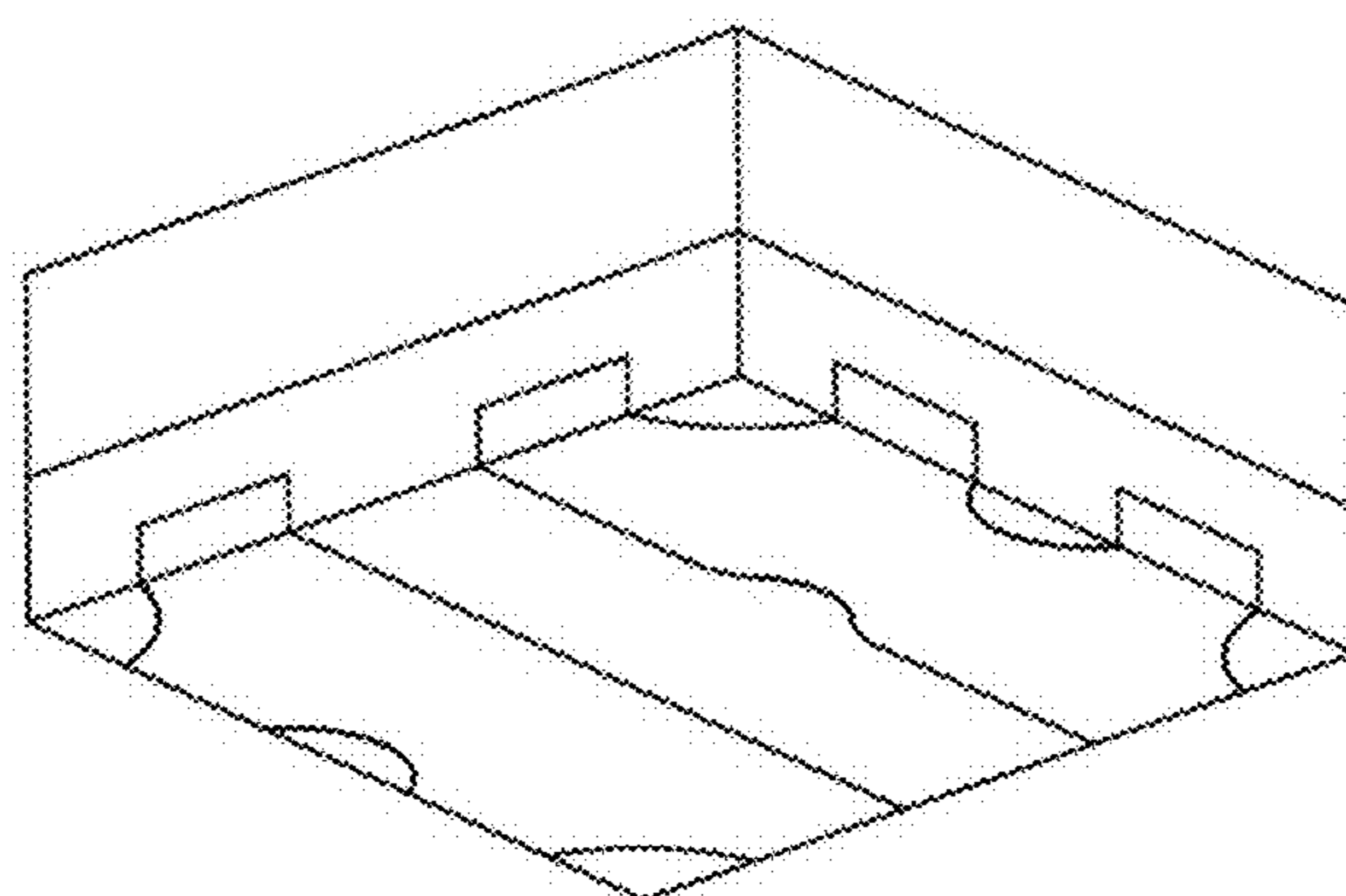


FIG. 16

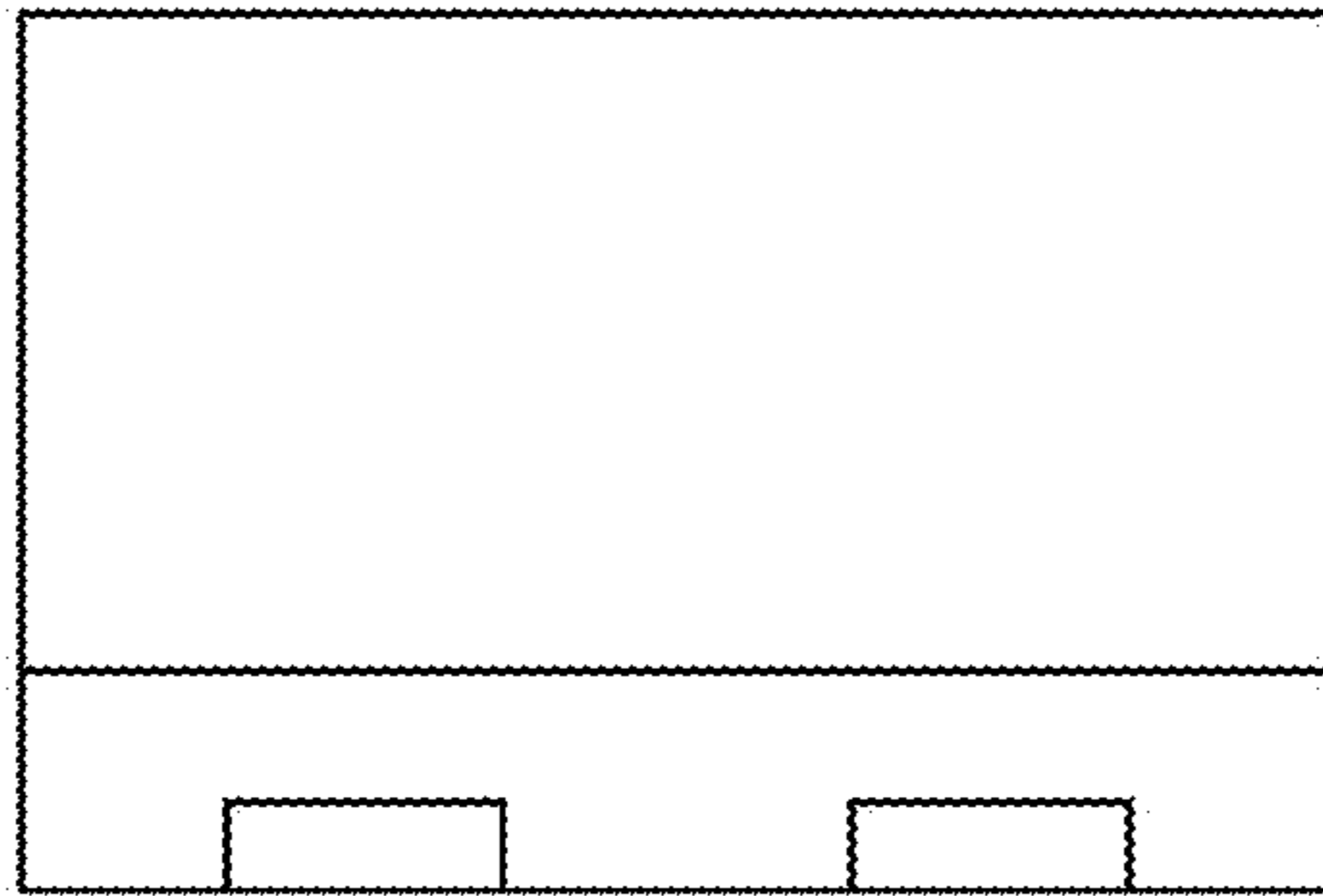


FIG. 17

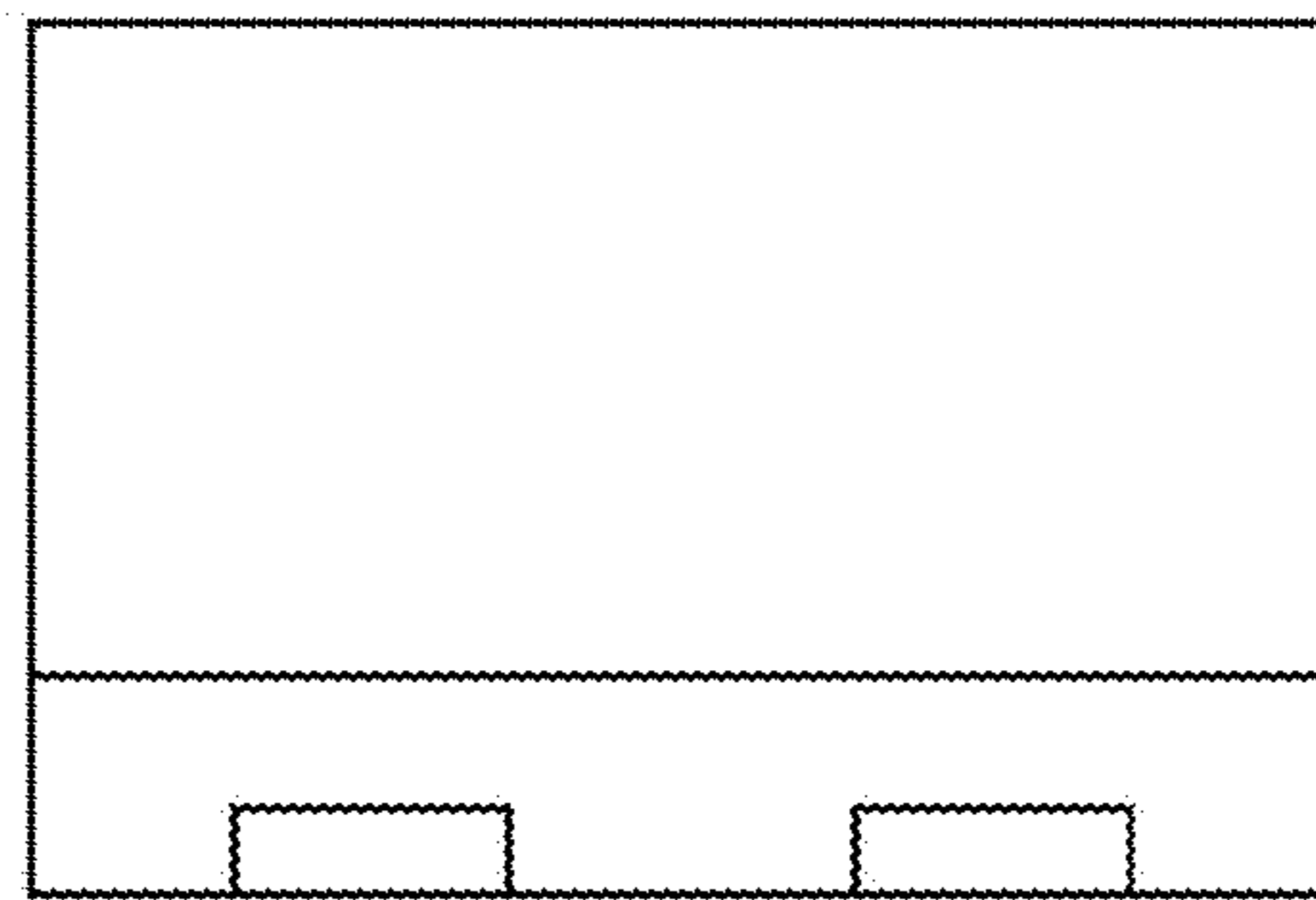


FIG. 18

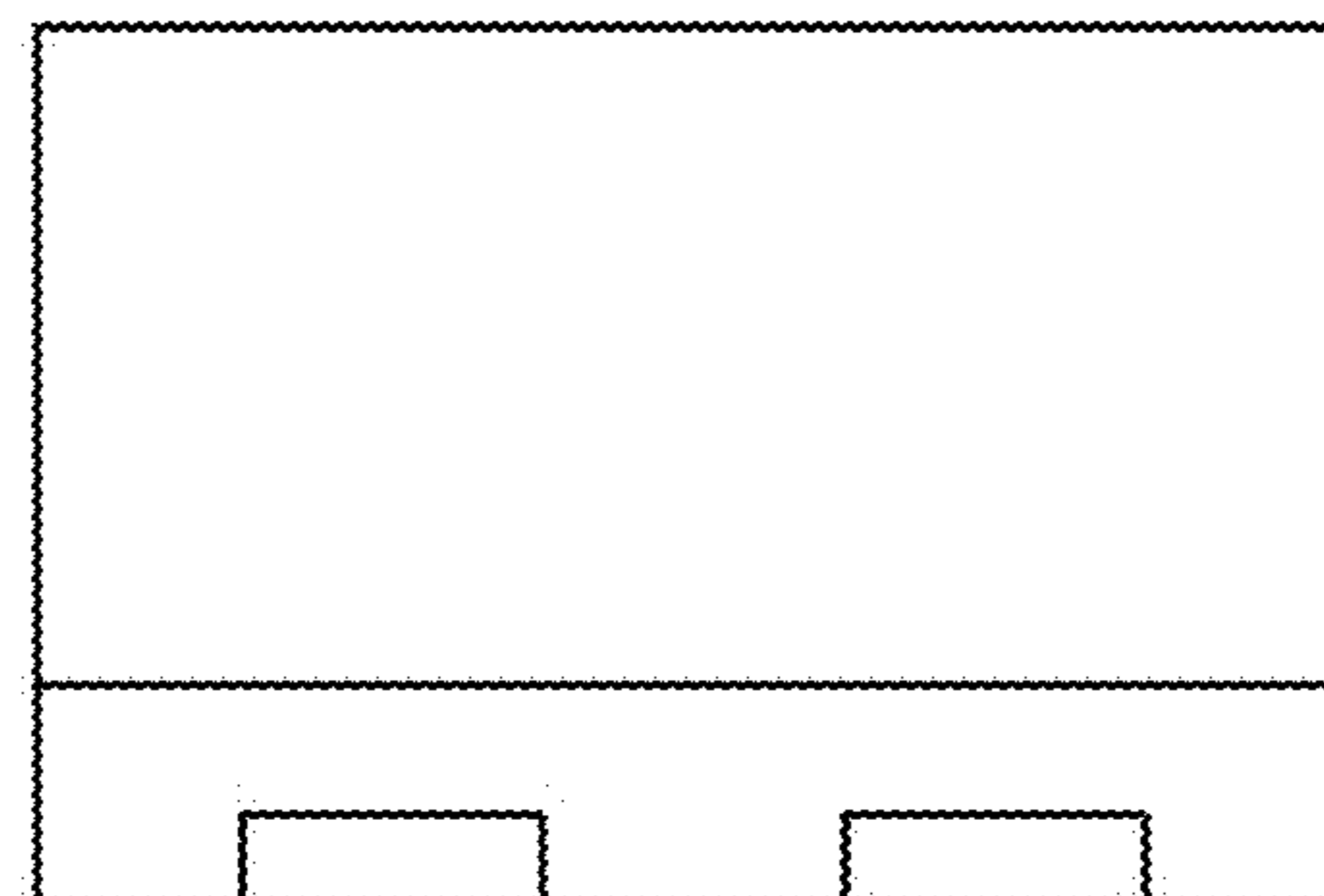


FIG. 19

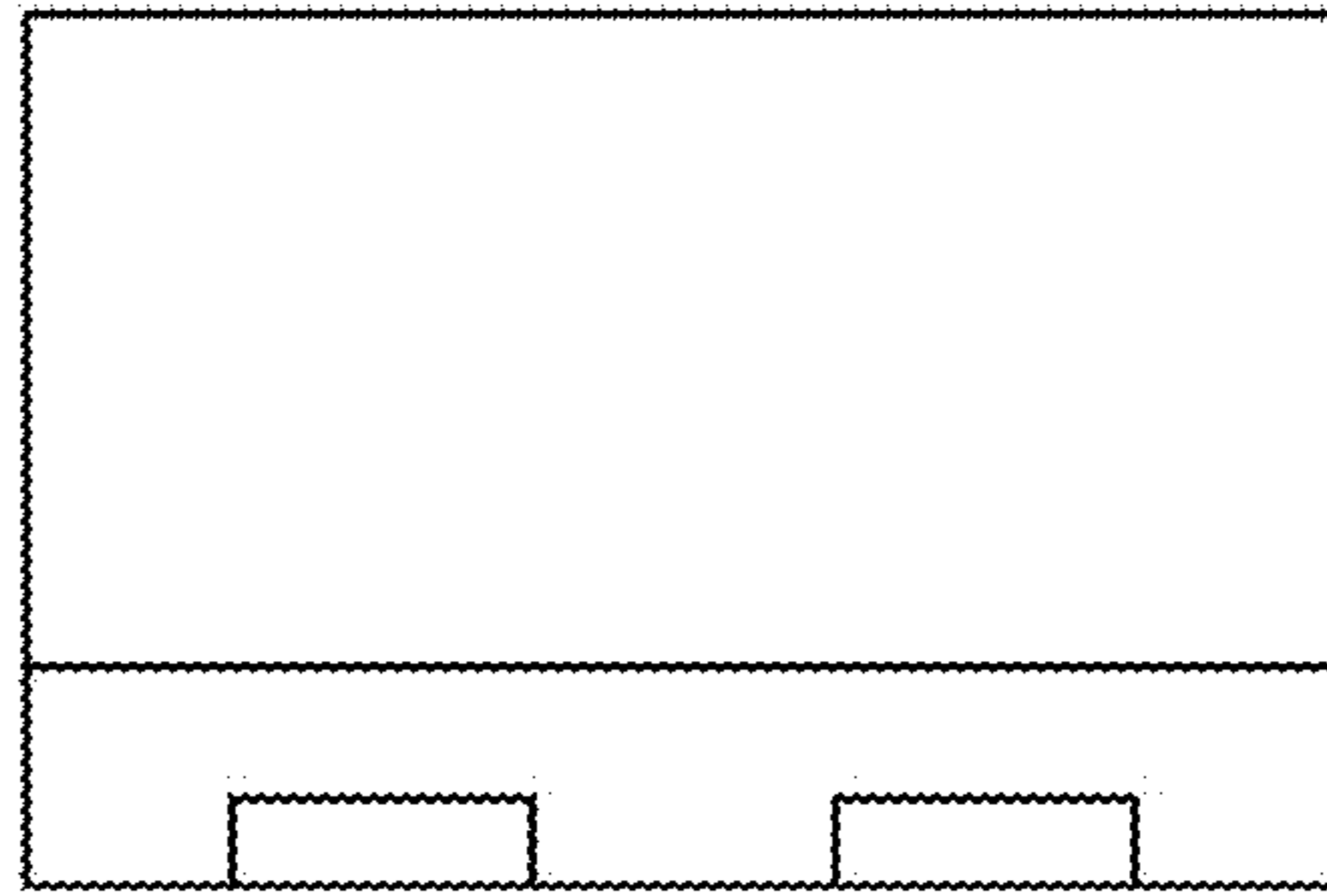


FIG. 20

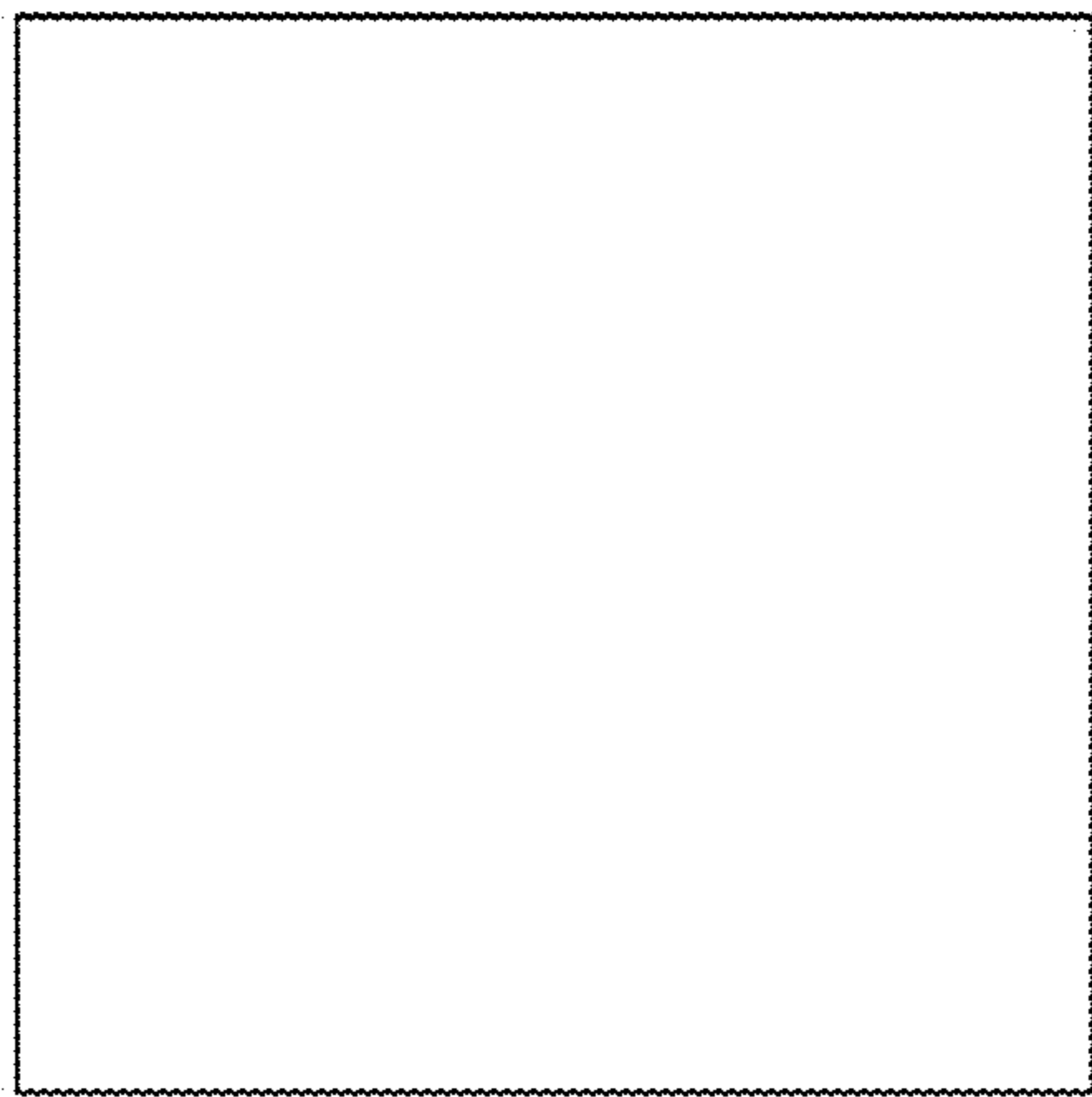


FIG. 21

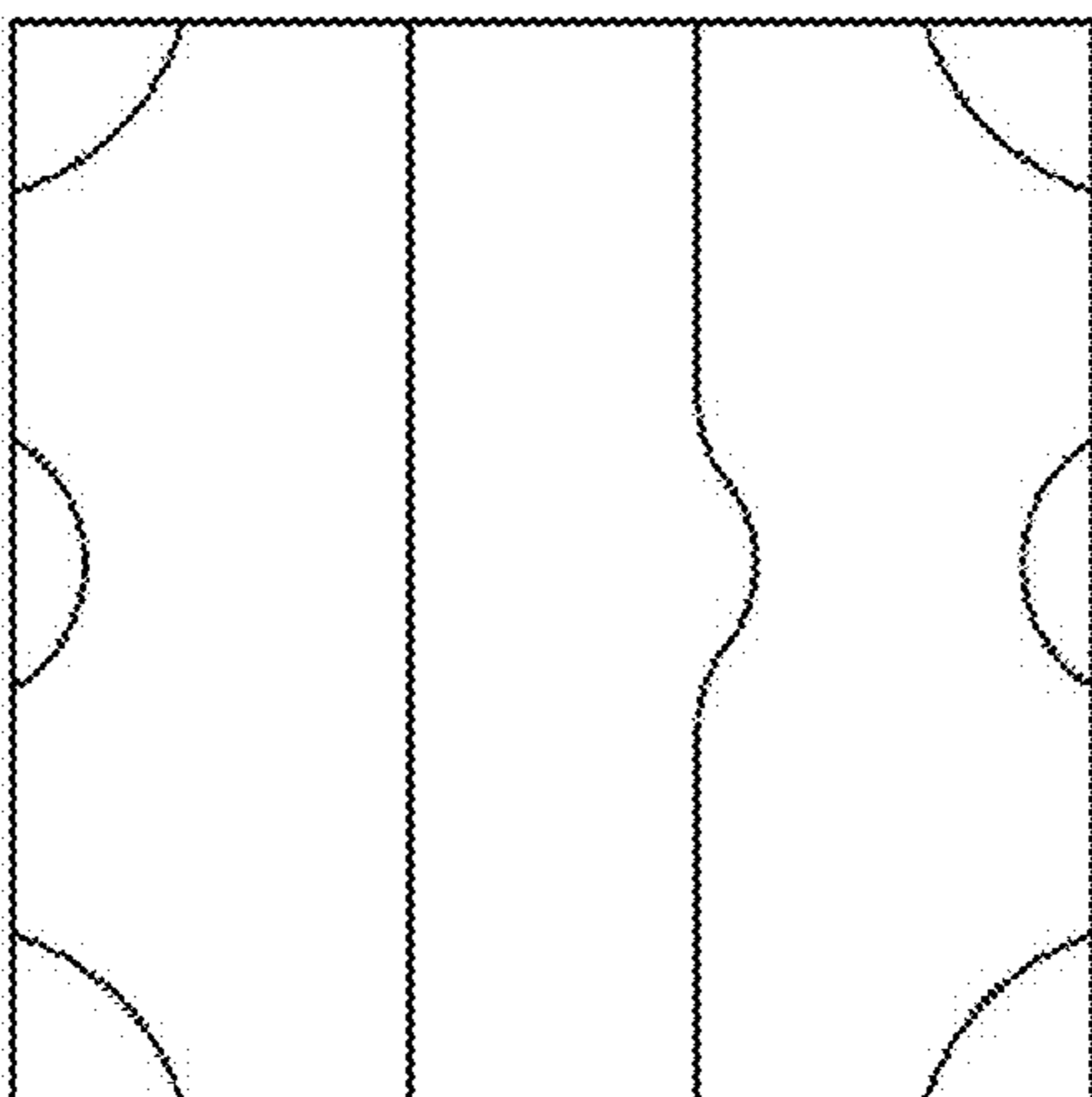


FIG. 22

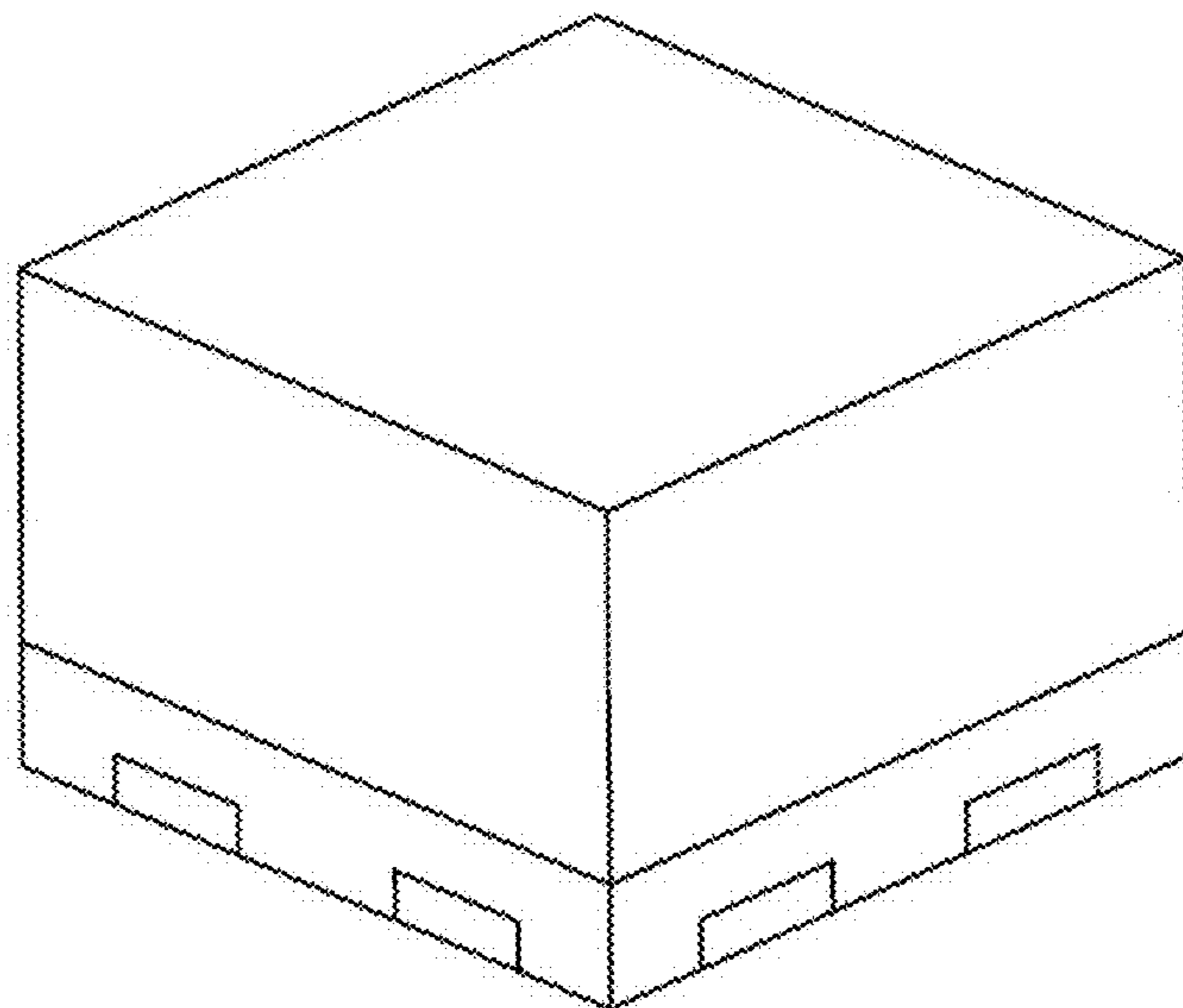


FIG. 23

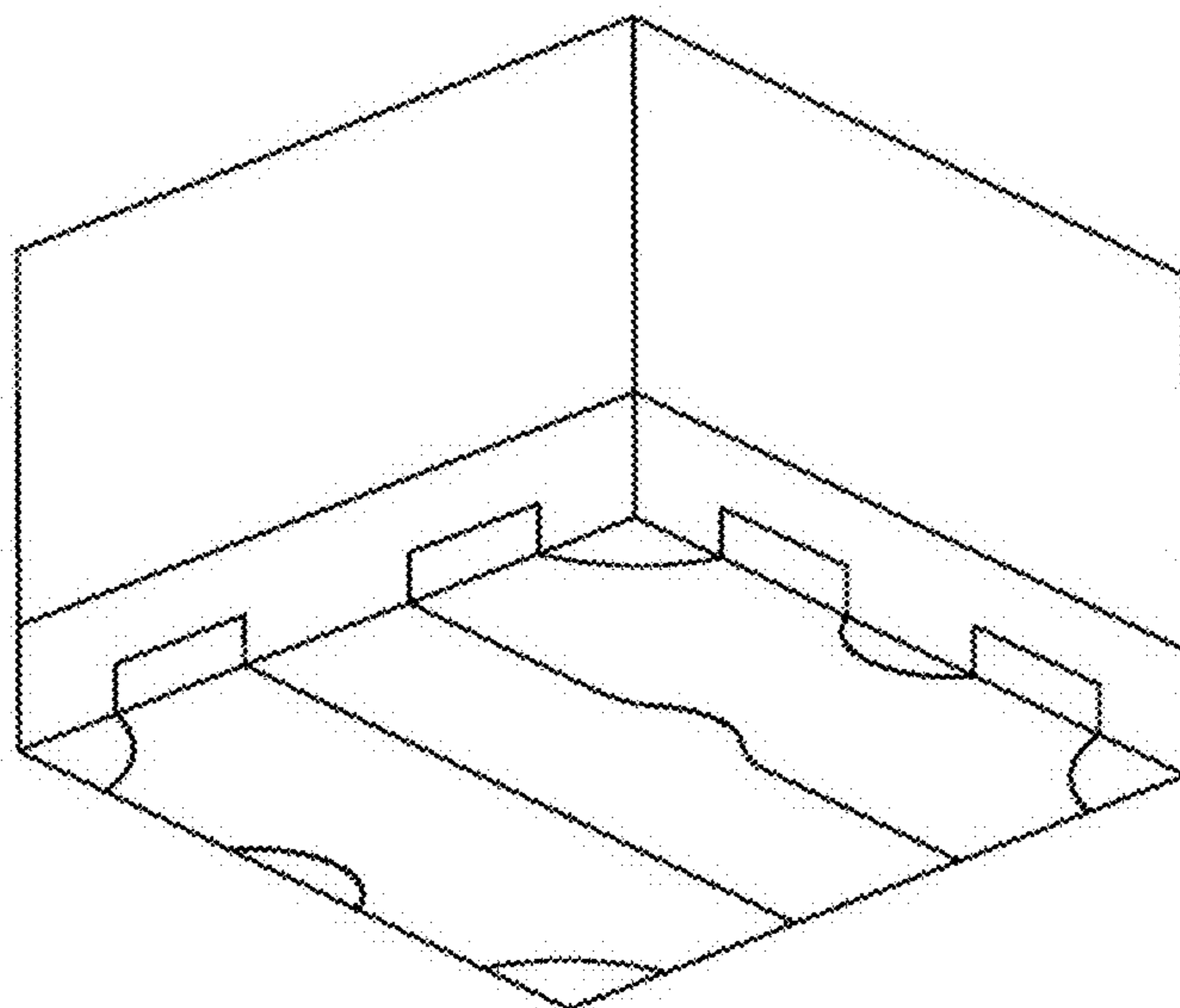


FIG. 24